

Applicants: Michael S. Leung, Confirmation No. 8955

et al.

10/666,399 Serial No.

Examiner: Le, Thao X

Filed: September 18, 2003

Art Unit: 2814

Docket No. P0298US-7

23935 Customer No.

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

REPLY TO THE FINAL OFFICE ACTION AND REQUEST FOR CONTINUED **EXAMINATION**

Sir:

In response to the Office Action mailed on February 14, 2007, please consider the remarks and arguments presented below and amend the above-identified application as follows:

AMENDMENTS TO THE CLAIMS are shown beginning on page 2 of this paper.

REMARKS AND ARGUMENTS begin on page 10 of this paper.